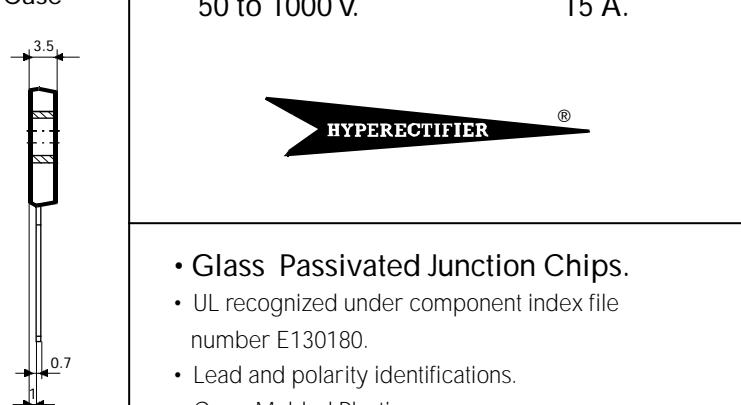


## 15 Amp. Glass Passivated Bridge Rectifier

Dimensions in mm.	Plastic Case 
 <ul style="list-style-type: none"> <li>High temperature soldering guaranteed: 260 °C – 10 sc.</li> <li>Recommended mounting torque: 8 Kg.cm.</li> </ul>	Voltage 50 to 1000 V.  Current 15 A. <ul style="list-style-type: none"> <li>Glass Passivated Junction Chips.</li> <li>UL recognized under component index file number E130180.</li> <li>Lead and polarity identifications.</li> <li>Case: Molded Plastic.</li> <li>Ideal for printed circuit board (P.C.B.).</li> <li>High surge current capability.</li> <li>The plastic material carries U/L recognition 94 V-O.</li> </ul>

## Maximum Ratings, according to IEC publication No. 134

		FBI15A 1M1	FBI15B 1M1	FBI15D 1M1	FBI15G 1M1	FBI15J 1M1	FBI15K 1M1	FBI15M 1M1
$V_{RRM}$	Peak recurrent reverse voltage (V)	50	100	200	400	600	800	1000
$V_{RMS}$	Maximum RMS voltage (V)	35	70	140	280	420	560	700
$I_{F(AV)}$	Max. Average forward current with heatsink without heatsink			15.0 A at 75 °C 3.2 A at 25 °C				
$I_{FSM}$	10 ms. peak forward surge current (Jedec Method)			200 A				
$I^2t$	Current squared time (rating for fusing) (1ms.< t <10ms. $T_c = 25^\circ\text{C}$ )			110 $\text{A}^2$ sec				
$V_{DIS}$	Dielectric strength (terminals to case, AC 1 min.)			2500 V				
$T_j$	Operating temperature range			– 55 to + 150 °C				
$T_{stg}$	Storage temperature range			– 55 to +150 °C				

Electrical Characteristics at  $T_{amb} = 25^\circ\text{C}$ 

$V_F$	Max. forward voltage drop per diode at $I_F = 7.5 \text{ A}$	1.10V
$I_R$	Max. instantaneous reverse current at $V_{RRM}$	5 $\mu\text{A}$
$R_{th(j-c)}$	MAXIMUM THERMAL RESISTANCE Junction-Case. With Heatsink.	2.2 °C/W
$R_{th(j-a)}$	Junction-Ambient. Without Heatsink.	22 °C/W

